

INTEGRATED CIRCUIT PACKAGE AND METHOD

Abstract of the Disclosure

5 An integrated circuit package(60) has a substrate (12)
with a first surface (51) for mounting a semiconductor die
(20) and a second surface (52) defining a via (70). A lead
(26) is formed by plating a conductive material to project
outwardly from the second surface. The conductive material
10 extends from the lead through the first via for coupling to
the semiconductor die.